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- Replaces SN74AS303
- Maximum Output Skew Between Same Phase Outputs of 1 ns
- Maximum Pulse Skew of 1 ns
- TTL-Compatible Inputs and Outputs
- Center-Pin V<sub>CC</sub> and GND Configurations Minimize High-Speed Switching Noise
- Package Options Include Plastic Small-Outline (D) Package and Standard Plastic (N) 300-mil DIPs

#### **DORNPACKAGE** (TOP VIEW) ] Q2 Q3 l 16 Q4 [] 15 Q1 GND 3 14 CLR GND [ 13 ] v<sub>cc</sub> GND 5 Q5 | 6 11 ∐ CLK Q6 L 10 PRE Q7 9 ] <del>Q</del>8

### description

The CDC303 contains eight flip-flops designed to have low skew between outputs. The eight outputs (six in-phase with CLK and two out-of-phase) toggle on successive CLK pulses. Preset ( $\overline{PRE}$ ) and clear ( $\overline{CLR}$ ) inputs are provided to set the Q and  $\overline{Q}$  outputs high or low independent of the clock (CLK) input.

The CDC303 has output and pulse-skew parameters  $t_{sk(0)}$  and  $t_{sk(p)}$  to ensure performance as a clock driver when a divide-by-two function is required.

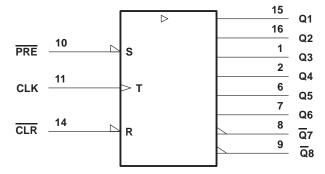
The CDC303 is characterized for operation from 0°C to 70°C.

#### **FUNCTION TABLE**

INPUTS			OUTPUTS		
CLR	PRE	CLK	Q1-Q6	Q7-Q8	
L	Н	Χ	L	Н	
Н	L	Χ	Н	L	
L	L	X	L†	L†	
Н	Н	$\uparrow$	$\overline{Q}_0$	$Q_0$	
Н	Н	L	Q <sub>0</sub>	$\overline{Q}_0$	

<sup>†</sup> This configuration does not persist when PRE or CLR returns to its inactive (high) level.

# logic symbol‡



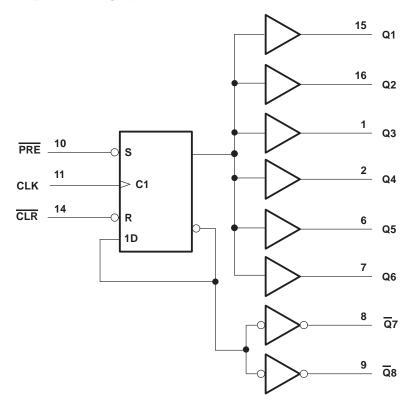
<sup>&</sup>lt;sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 1): D package	0.77 W
N package	1.2 W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
ІОН	High-level output current			-24	mA
loL	Low-level output current			48	mA
fclock	Input clock frequency			80	MHz
T <sub>A</sub>	Operating free-air temperature	0		70	°C



NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2	V
Vou	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2	2		V
VOH	V <sub>CC</sub> = 4.5 V,	$I_{OH} = -24 \text{ mA}$	2	2.8		V
VOL	V <sub>CC</sub> = 4.5 V,	$I_{OL} = 48 \text{ mA}$		0.3	0.5	V
lį	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1	mA
lН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.4 V			-0.5	mA
IO <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-50		-150	mA
Icc	V <sub>CC</sub> = 5.5 V,	See Note 2		40	70	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature

			MIN	MAX	UNIT
fclock	Clock frequency		0	80	MHz
		CLR or PRE low	5		
t <sub>w</sub>	Pulse duration	CLK high	4		ns
		CLK low	6		
t <sub>su</sub>	Setup time before CLK↑	CLR or PRE inactive	6		ns

## switching characteristics over recommended operating free-air temperature range (see Figure 1)

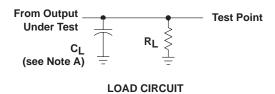
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
f <sub>max</sub> §				80		MHz
t <sub>PLH</sub>	CLK	Q, $\overline{\mathbb{Q}}$	$R_L = 500 \Omega$ , $C_L = 50 pF$	2	9	ns
<sup>t</sup> PHL	OLK	Q, Q	NC = 300 s2,	2	9	115
<sup>t</sup> PLH	PRE or CLR	$Q, \overline{Q}$	$R_L = 500 \Omega$ , $C_L = 50 pF$	3	12	ns
<sup>t</sup> PHL	PRE OF CLR	Q, Q	KL = 300 22,	3	12	115
	CLK	Q			1	ns
t <sub>sk(o)</sub>		L Q	$R_L$ = 500 Ω, $C_L$ = 10 pF to 30 pF, See Figure 2		1	
		Q, <u>Q</u>	See Figure 2			
<sup>t</sup> sk(p)	CLK	Q, <del>Q</del>	$R_L = 500 \Omega$ , $C_L = 10 pF to 30 pF$		1	ns
t <sub>r</sub>					4.5	ns
t <sub>f</sub>					3.5	ns

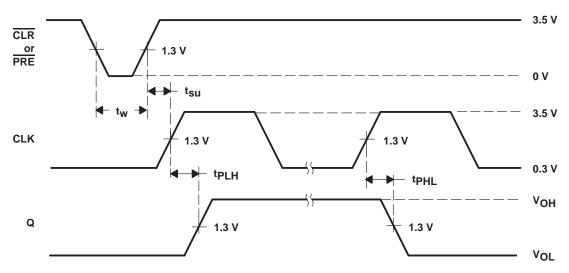
<sup>§</sup> f<sub>max</sub> minimum values are at C<sub>L</sub> = 0 to 30 pF.



<sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, Ios. NOTE 2: Icc is measured with CLK and PRE grounded, then with CLK and CLR grounded.

### PARAMETER MEASUREMENT INFORMATION





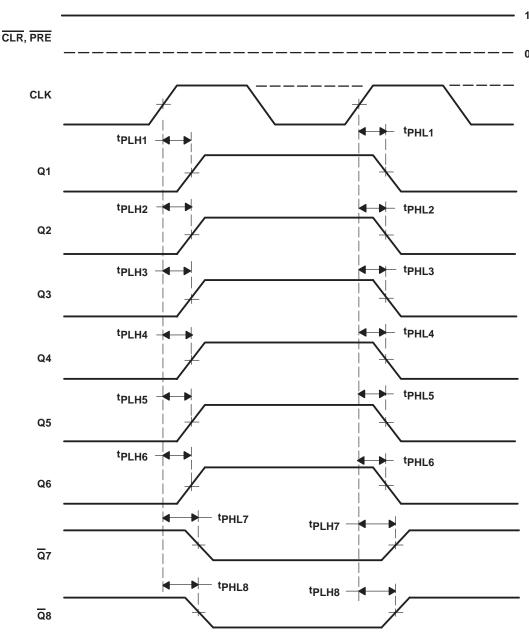
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $t_r = 2.5$  ns,  $t_f = 2.5$  ns.

Figure 1. Load Circuit and Voltage Waveforms



### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $t_{Sk(0)}$ , CLK to Q, is calculated as the greater of:

- The difference between the fastest and slowest of  $t_{PLHn}$  ( n = 1, 2, 3, 4, 5, 6)
- The difference between the fastest and slowest of tpHLn ( n = 1, 2, 3, 4, 5, 6)
- B.  $t_{sk(0)}$ , CLK to  $\overline{Q}$ , is calculated as the greater of: |  $t_{PLH7} t_{PLH8}$  | and |  $t_{PHL7} t_{PHL8}$  |. C.  $t_{sk(0)}$ , CLK to  $\overline{Q}$  and  $\overline{Q}$ , is calculated as the greater of:
- - The difference between the fastest and slowest of tp<sub>LHn</sub> (n = 1, 2, 3, 4, 5, 6), tp<sub>HL7</sub>, and tp<sub>HL8</sub>
  - The difference between the fastest and slowest of tpHLn ( n = 1, 2, 3, 4, 5, 6), tpLH7, and tpLH8
- D.  $t_{Sk(p)}$  is calculated as the greater of  $|t_{PLHn} t_{PHLn}|$  ( n = 1, 2, 3, ..., 8 ).

Figure 2. Waveforms for Calculation of  $t_{sk(p)}$  and  $t_{sk(p)}$ 





### PACKAGE OPTION ADDENDUM

2-May-2005

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CDC303D	ACTIVE	SOIC	D	16	Green (RoHS & no Sb/Br)	CU NIPD	Level-1-260C-UNLIM
CDC303DR	ACTIVE	SOIC	D	16	Green (RoHS & no Sb/Br)	CU NIPD	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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